



HY-264018 Bluetooth BLE v4.1 Module Specifications

(22 pin)

23 Oct. 2017

Version : V1.0

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1. Description

HY-264018 Bluetooth low energy single mode module is a single mode device targeted for low power sensors and accessories.

HY-264018 offers all Bluetooth low energy features: radio, stack, profiles and application space for customer applications. The module also provides flexible hardware interfaces to connect sensors.

HY-264018 can be powered directly with a standard 3V coin cell batteries or pair of AAA batteries. in lowest power shutdown mode it consumes only 0.15uA and will wake up in few microseconds.

HY-264018 transmission distance of 100 meter. (At face to face, free space, 1.2 Meter high from Ground for testing).

Bluetooth IC : TI CC2640 5*5*0.9mm 32pin IC

1-1.APPLICATIONS:

Heart rate sensors
Pedometers
Watches
Blood pressure and glucose meters
Weight scales
Key fobs
Households sensors and collector devices
Security tags
Wireless keys (keyless go)
Proximity sensors
HID keyboards and mice
Indoor GPS broadcasting devices

1-2.KEY FEATURES:

- Bluetooth BLE v.4.1 single mode compliant
- Supports master,slaveand master/slave modes
- Integrated Bluetooth low energy stack
- GAP, GATT, L2CAP, SMP Bluetooth low energy profiles
- Compliance: BQB BLE4.1,FCC,IC(Canada),CE ETSI RED...etc. worldwide RF Regulations.
- Transmit power :+5 dBm typical
- Receiver sensitivity: -97dBm typical
- Ultra low current consumption :Shutdown. No clocks running, no retention: 150 nA(Typical)
- Programmable ARM Cortex-M3 processor for embedding full applications

2. Product model Number: Hardware Model Description

2-1. (4 kinds Antenna type for choice) ,(Option: with shield case or no shield case)

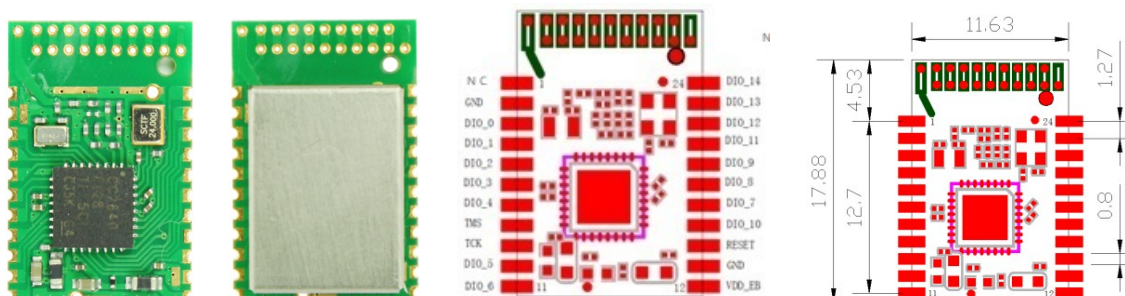
	Product Mode Item	PCB NO.	Description
1	WMD400018SR6P0	HY-264018P	PCB Helix Antenna
2	WMD400018SR6I0	HY-264018I	IPEX Connector for External Antenna
3	WMD400018SR6W0	HY-264018W	Metal Wire Antenna
4	WMD400018SR6C0	HY-264018C	Ceramic Antenna
6	WMD400018SR6PC	HY-264018PC	PCB Helix Antenna with shield case
5	WMD400018SR6IC	HY-264018IC	IPEX Connector for External Antenna with shield case
7	WMD400018SR6WC	HY-264018WC	Metal Wire Antenna with shield case
8	WMD400018SR6CC	HY-264018CC	CeramicAntenna with shield case

3. PCBA dimension size and picture

3-1: HY-264018P / WMD400018SR6P0(PCB Helix Antenna)

&HY-264018PC / WMD400018SR6PC (PCB Helix Antenna, with shield case);

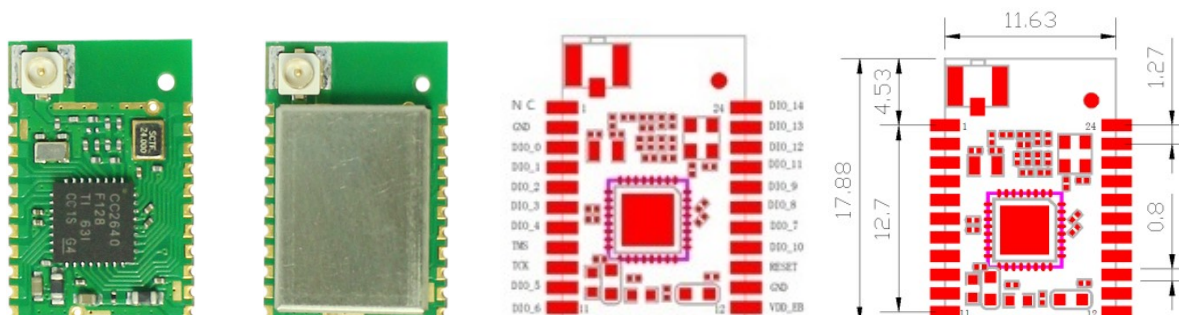
(PCBA dimension size : 17.88*11.63*2.0/2.6 mm).



3-2:HY-264018I / WMD400018SR6I0(IPEX RF connector terminal)

&HY-264018IC / WMD400018SR6IC (IPEX RF connector with shield case)

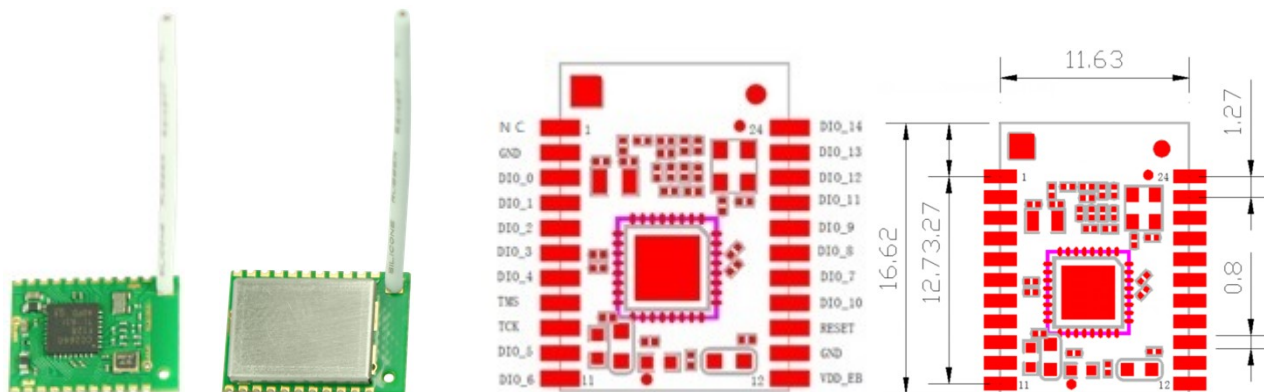
(PCBA dimension size : 17.88*11.63*2.6 mm).



3-3: HY-264018W / WMD400018SR6W0(Metal WireAntenna)(1/4 λ half wave dipole)_

&HY-264018WC / WMD400018SR6WC (Metal Wire Antenna, with shield case) ;

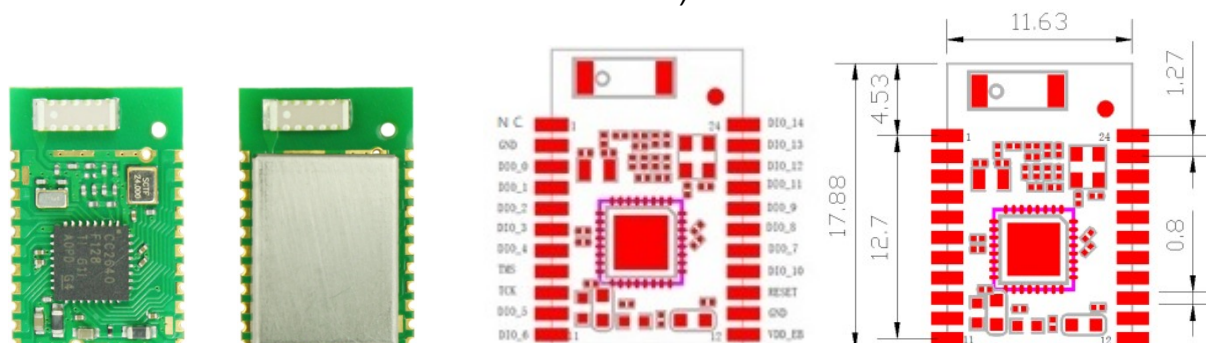
(PCBA dimension size : 16.62*11.63*2.0/2.6 mm).



3-4: HY-264018C / WMD400018SR6C0(CeramicAntenna)

&HY-264018CC / WMD400018SR6CC (Ceramic Antenna, with shield case) ;

(PCBA dimension size : 17.88*11.63*2.0/2.6 mm).



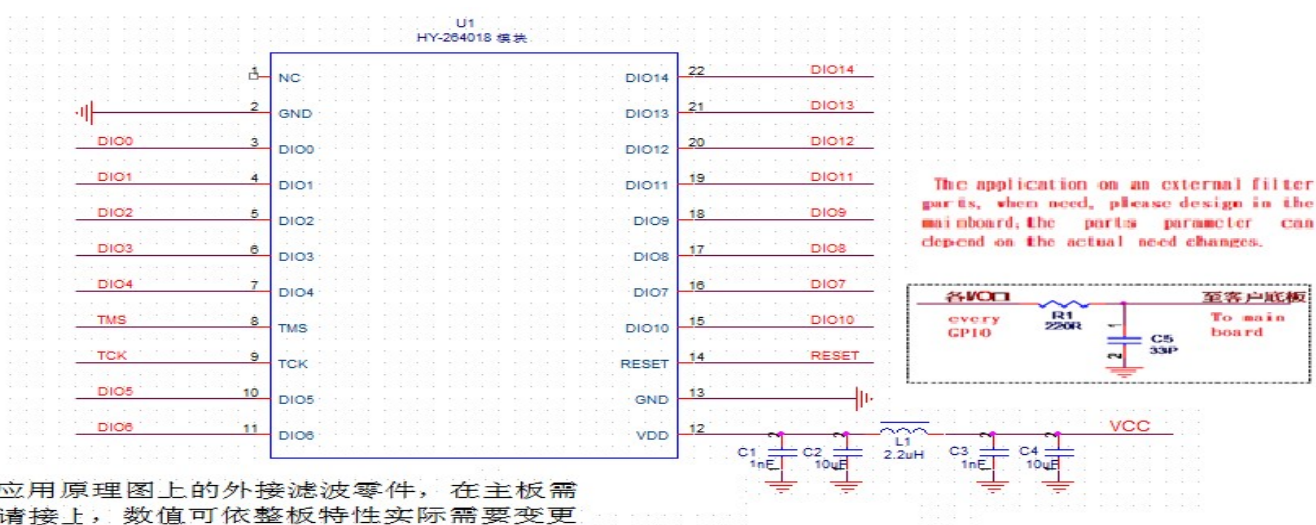
4.Application Note:

- 4-1. Attention to the electrostatic protection, prevent the soldering iron and the equipment grounding bad; And the workbench, working environment, packaging materials and from the human body Touch with static electricity, etc., destroy IC and software be fly; Manual welding module solder iron temperature, should pay attention to avoid the PCB copper stripping off; Soldering iron strictly Grounding requirements, eliminating iron power failure module;
- 4-2. Attention to avoid the overall motherboard power supply circuit of bad welding connected to short circuit or open circuit, causing the Bluetooth chip, abnormal voltage, The software will fly and problems of IC was damaged.
- 4-3. When programming firm ware , the VDDDS supply voltage must in DC 2.4~3.3V, To avoid programming has not completely, and abnormal status occur..
- 4-4. Use the module in the production and the transport process, please insure module's component protection, prevent the precision parts on the module Damaged (welding furnace exit and assembly, testing, delivery process, suggest using collision buffer material, not collide with each other)

4-5. The module for the humidity sensitive components, if used in SMT reflow soldering operations, please strictly follow the IPC/JEDECJ - STD – 020 regulation, completes the drying dehumidifying , and for this module has second processing work after placed in the functional test environment, the humidity of the chip is no guarantee that in a certain ratio, the honored guest please understand;(The attention note show in below Fig.)



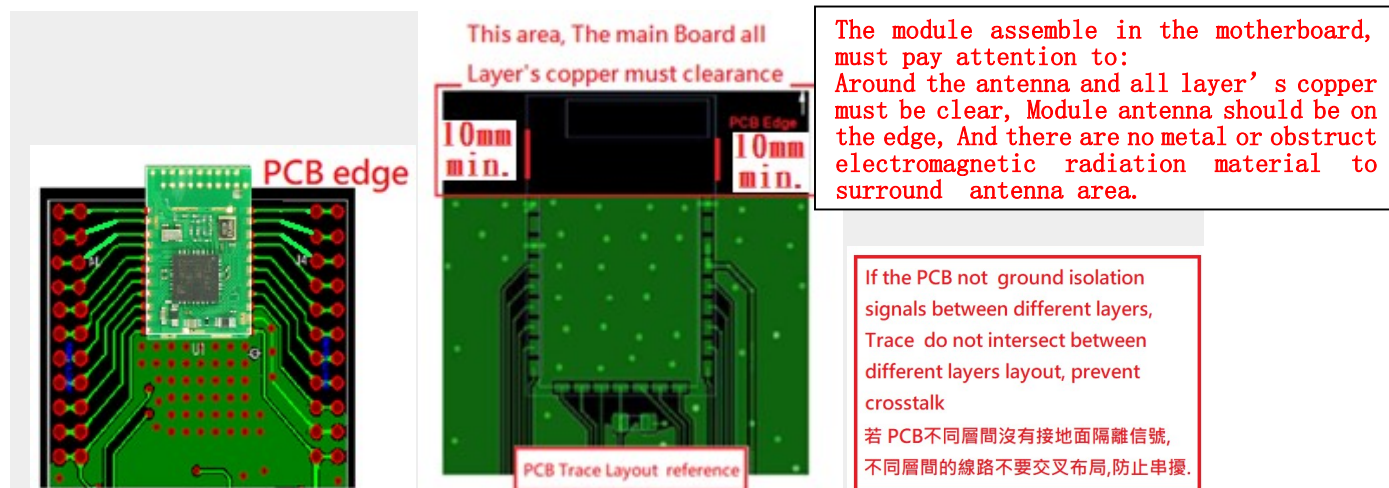
4-6. The diagram (show in below Fig.) of the module application on external filter parts, whenneed, please design in the mainboard, the parts parameter can depend on the actual need to changes.



模块应用原理图上的外接滤波零件，在主板需要时请接上，数值可依整板特性实际需要变更

4-7.Assembly recommendation 1:Underneath the module antenna and RF circuit on themain board PCB copper need to clearance, and place close to the main board edge, as show in below Fig. The antenna can't be near around metal parts and prevent material existence of electromagnetic radiation , Can affect the manipulation of the distance

4-8 Assembly recommendation 2:Signal trace and power supply trace, don't cross layout, as show in below Fig.To avoid crosstalk, affect the receiving sensitivity.



5. Pinout and GPIO function Description

Pin No.	Name	Type	Function Description
1	NC	NC	Not connect
2	GND	Power GND	Ground
3	DIO_0	Digital I/O	GPIO, Sensor Controller (I:4mA max),
4	DIO_1	Digital I/O	GPIO, Sensor Controller (I:4mA max),
5	DIO_2	Digital I/O	UART RX/MISO /GPIO, Sensor Controller, high-drive capability (I:8mA max)
6	DIO_3	Digital I/O	UART TX/MOSI/GPIO, Sensor Controller, high-drive capability (I:8mA max)
7	DIO_4	Digital I/O	Wake Up , Don't floating. GPIO, Sensor Controller.high-drive capability (8mA max).
8	JTAG TMS	Digital I/O	JTAG TMS; high-drive capability(8mA max)
9	JTAG TCK	Digital I/O	JTAG TCK
10	DIO_5 TDO	Digital I/O	INT/JTAG_TDO, GPIO, high-drive capability(8mA max)
11	DIO_6 TDI	Digital I/O	JTAG_TDI, GPIO, high-drive capability(8mA max)
12	VDD	Power Supply	+1.8V to +3.8V (Recommended 2.7~3.3V)
13	GND	Power GND	Ground
14	RESET_N	Digital input	Reset, active-low. Module have pull up.
15	DIO_10	Digital I/O	GPIO, Sensor Controller, Analog(I: 4mA max)
16	DIO_7	Digital I/O	GPIO, Sensor Controller, Analog(I: 4mA max)
17	DIO_8	Digital I/O	GPIO, Sensor Controller, Analog(I: 4mA max)
18	DIO_9	Digital I/O	GPIO, Sensor Controller, Analog(I: 4mA max)
19	DIO_11	Digital I/O	GPIO, Sensor Controller, Analog(I: 4mA max)
20	DIO_12	Digital I/O	GPIO, Sensor Controller, Analog(I: 4mA max)
21	DIO_13	Digital I/O	GPIO, Sensor Controller, Analog(I: 4mA max)
22	DIO_14	Digital I/O	GPIO, Sensor Controller, Analog(I: 4mA max)

6. Electrical Characteristics

(Test condition: With Ta = 25 °C, VDD =3.0V with internal DC-DC converter, standardmeasure:1Mbps GFSKmodulation ,FRF = 2440MHz Bluetooth Low energy mode.)

6-1.Radio performance & current consumption

(Test condition:With Ta = 25 °C, VDD =3.0V, with internal DC-DC converter, standardmeasure:1Mbps GFSKmodulation ,FRF = 2440MHz Bluetooth Low energy mode.)

- Modulation Mode: GFSK
- Frequency range: 2402~2480MHZ (2.4GHz ISM band)
- Transmit power setting Range: -21 ~ +5 dBm typical (differential mode o/p point characteristics ; programmable by software)
- Receiver sensitivity: -97dBm typical(differential mode o/p point characteristics)
- Compliance: FCC,IC(Canada),CE ETSI RED,BQB,... etc. worldwide RF Regulations.
- Ultra low current consumption
 - Transmit : 6.1mA(typical) (O/P Power setting :0dBm)
 - Transmit : 9.1mA(typical) (O/P Power setting :5dBm)
 - Receive(high gain setting): 6.1 mA(typical)
 - Idle. Supply Systems and RAM powered:550uA(Typical)
 - Standby. With Cache, RTC, CPU, RAM and partial register retention. XOSC_LF: 3.0 uA(Typical)
 - Shutdown. No clocks running, no retention: 150 nA(Typical)

6-2. Absolute Maximum Ratings

Note: These are absolute maximum ratings beyond which the module can be permanently damaged, these are not Maximum operating conditions, the maximum recommended operating conditions are in the table 6.

Rating	Min	Max	Unit
VDDS	-0.3	4.1	V
Other Terminal Voltages	VSS-0.3	VDDS+0.3	V
Storage Temperature	-40	+85	°C

6-3. ESD Ratings

			Value	Unit
VESDElectrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDECJS001	All pins	±2500	V
	Charged device model (CDM), per JESD22-C101	RF pins	±750	
		Non-RFpins	±750	

6-4. Recommended Operating Conditions

Supply voltage noise should be less than 10mVpp. Excessive noise at the supply voltage will reduce the RF performance.

Rating	Min	Max	Unit
VDD (when BlueTooth Active)	1.8	3.8	V
VDD(when flash programming)	2.4	3.3	V
Operating Temperature Range	-40	+85	°C

Note: (1).VDD power supply recommended voltage : 2.7~3.3V

(2).When programming firm ware , the VDD supply voltage must in DC 2.4~3.3V,

To avoid programming has not completely, or abnormal status occur..

(3).For smaller coin cell batteries, with high worst-case end-of-life equivalent source resistance, a 22-μF VDDS input capacitor must be used to ensure compliance with this slew rate(6-6 timing req.).

6-5.GPIODC Characteristics

Parameter	Test Condition	Typical	Unit
GPIO VOH at 8-mA load	IOCURR = 2, high-drive GPIOs only	2.68	V
GPIO VOL at 8-mA load	IOCURR = 2, high-drive GPIOs only	0.33	V
GPIO VOH at 4-mA load	IOCURR = 1	2.72	V
GPIO VOL at 4-mA load	IOCURR = 1	0.28	V

6-6. Timing Requirements

Description		MIN	NO M	MA X	UNIT
Rising supply-voltage slew rate		0		100	mV/uS
Falling supply-voltage slew rate		0		20	mV/uS
Falling supply-voltage slew rate, with low-power flash settings(1)				3	mV/uS
Positive temperature gradient in standby(2)	No limitation for negative temperature gradient, or outside standby mode			5	°C/s
CONTROL INPUT AC CHARACTERISTICS(3)					
RESET_N low duration		1			uS

(1) For smaller coin cell batteries, with high worst-case end-of-life equivalent source resistance, a 22-μF VDDS input capacitor must be used to ensure compliance with this slew rate.

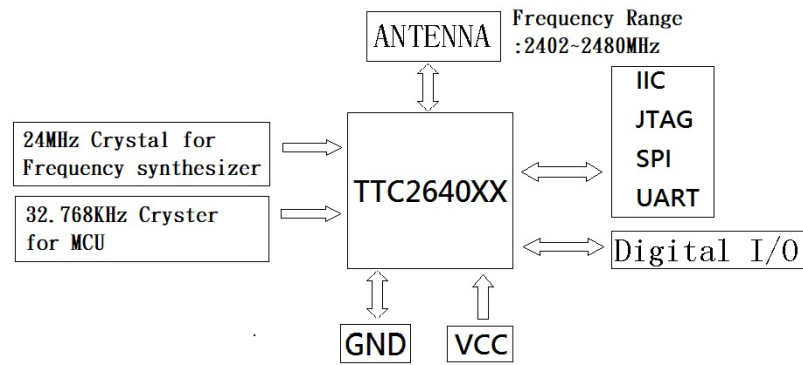
(2) Applications using RCOSC_LF as sleep timer must also consider the drift in frequency caused by a change in temperature .

6-7. Switching Characteristics

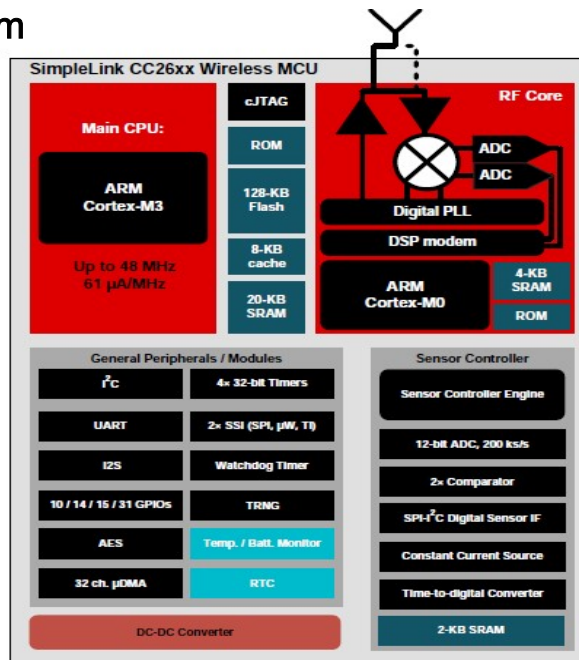
Measured with Tc = 25°C, VDDS = 3.0 V, unless otherwise noted.

Parameter	Test Condition	Min	Typical	Max	Unit
Wakeup and Timing					
Idle →Active			14		μs
Standby →Active			151		μs
Shutdown →Active			1015		μs

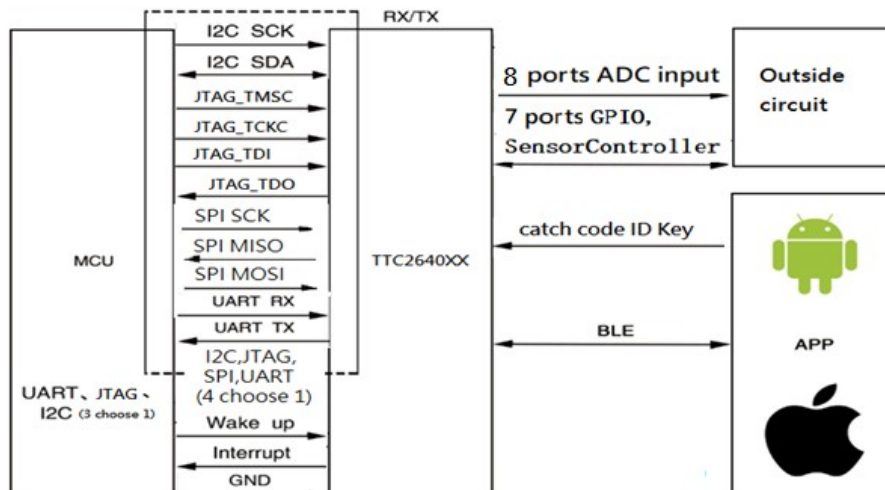
7. Block Diagram



8. Functional Block Diagram



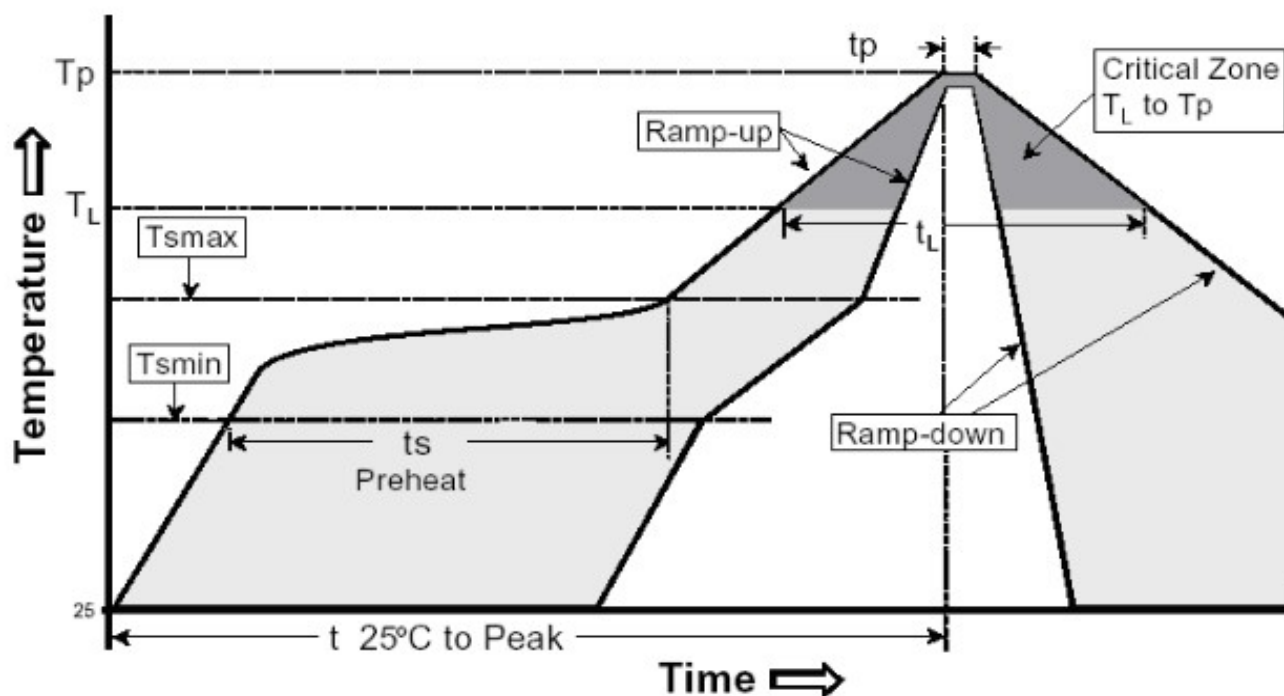
9. Working mode schematic :



10. Recommend Reflow Profile(Leadless solder cream: Sn 96.5%, Ag 3%, Cu 0.5%)

Profile Feature	Pb-Free Assembly	
	Large Body	Small Body
Average ramp-up rate(T_L to T_P)	3°C/second max	
Preheat-Temperature Min (T_{smin})	150°C	
-Temperature Max (T_{smax})	200°C	
-Time (min to max)(t_s)	60-180 seconds	
T_{smax} to T_L -Ramp-up Rate	3°C/second max	
Time maintained above-Temperature (T_L)	217°C	
-Time (t_L)	60-150 seconds	
Peak Temperature (T_P)	245 +0/-5°C	250 +0/-5°C
Time within 5°C of actualPeakTemperature (t_p)	10-30 seconds	20-40 seconds
Ramp-down Rate	6°C/second max	
Time 25°C to PeakTemperature	8 minutes max	

Reflow Curve Classification



11.Contact Us

ShenZhenShengRun Technology Co.,Ltd.

Phone : +86-755-86233846

Fax:+86-755-82970906

Official Website : www.tuner168.com

Alibaba Website : <http://shop1439435278127.1688.com>

E-mail: marketing@tuner168.com

Address: Room 602,B Block of Longjing Jingu Hi-tech Pioneer Park, Longzhu 4th Road, Xili Town, Nanshan District, Shenzhen, Guangdong, China.

